

Bill of Materials

TI DESIGNS TIDA-00206

Item	Designator	Qty	Part Description	Manufacturer	Manufacturer Part Number
1	C1, C2, C5, C6	4	CAP, CERM, 1uF, 16V, +/-10%, X5R, 0603	Kemet	C0603C105K4PACTU
2	C3	1	CAP, CERM, 0.01uF, 50V, +/-10%, X7R, 0603	Kemet	C0603C103K5RACTU
3	C4	1	CAP, CERM, 2.2uF, 6.3V, +/-20%, X5R, 0603	TDK	C1608X5R0J225M080AB
4	C7	1	CAP, CERM, 1000pF, 50V, +/-10%, X7R, 0603	Kemet	C0603C102K5RACTU
5	D1, D2	2	LED 7-SEG .56 QUAD GRN CA MULT	Lumex Opto/Components Inc	LDQ-M512RI
6	P1	1	Header, TH, 100mil, 4x1, Gold plated, 230 mil above insulator	Samtec, Inc.	TSW-104-07-G-S
7	P2	1	Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	Samtec, Inc.	TSW-102-07-G-S
8	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8	8	Transistor, PNP, 40V, 0.2A, SOT-23	Fairchild Semiconductor	MMBT3906
9	R1, R2, R3, R4, R5, R6, R7, R8	8	RES, 10k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060310K0JNEA
10	R9, R10, R11, R12, R13, R14, R15, R16	8	RES, 4.7k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06034K70JNEA
11	R17, R18, R19, R20, R21, R22, R23, R24	8	RES, 27k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060327K0JNEA
12	R25, R26, R27, R28, R29, R30, R31, R32	8	RES, 1.0k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW06031K00JNEA
13	R33	1	RES, 47k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060347K0JNEA
14	R34, R35, R36, R37, R38, R39, R40	7	RES, 0 ohm, 5%, 0.1W, 0603	Panasonic	ERJ-3GEY0R00V
15	S1	1	Tactile switches 3.9x2.9x2.0mm 160gf	Alps	SKRKAEE010
16	U1	1	IC REG LDO 3.3V 0.15A SOT23-5	Texas Instruments	LP2985-33DBVR
17	U2, U3	2	IC MOTOR DRIVER 8 LOW SIDE	Texas Instruments	DRV8860PWR
18	U4	1	IC MCU 16BIT 4KB FLASH 16QFN	Texas Instruments	MSP430G2302IRSA16R

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